Investigation of physical properties of epoxy molding compounds with triphenylphosphine complex as the latent catalyst

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Latent catalysts were investigated to imporve the physical properties of epoxy molding compounds. In this study, biphenol type resins were used as the epoxy and hardener resin to obtain high flame retardant properties and high filler contents. Latent catalysts were examined with different epoxy molding compounds. We used triphenylphosphine (TTP) complex as a latent catalyst. The cure kinetics of these systems was investigated by differential scanning calorimetry with an isothermal approach to explain these phenomena.